

Epoxies, Ect. 10-3782

Epoxy; Epoxide

Epoxies, Etc.

Message:

These one component heat cure epoxy adhesives are fast setting materials formulated in three different viscosities. They are known for their low temperature cure, heat and excellent chemical resistance.

Very low viscosity

These unique adhesives exhibit outstanding bond strengths to a variety of substrates including metals, ceramics, wood, magnets, plastics, glass, etc... They are currently used in a variety of electronic bonding and potting applications, filer end cap assemblies, magnetic bonding applications and anywhere a tough indestructible bond is required.

General Information		
Features	Bondability	
	Fast Cure	
	Good Adhesion	
	Good Chemical Resistance	
	Low Viscosity	
	Medium Heat Resistance	
Uses	Adhesives	
	Bonding	
	Caps	
Appearance	Grey	
Processing Method	Encapsulating	
	Potting	
Additional Information	Nominal Value	Unit
Operating Temperature	-50.0 to 180	°C
Uncured Properties	Nominal Value	Unit
Color	Grey	
Solids Content	100	%
Density (25°C)	1.49	g/cm ³
Viscosity (25°C)	25	Pa · s
Curing Time		
175°C	0.030	hr
160°C	0.083	hr
121°C	0.25	hr
100°C	2.0	hr
Shelf Life		
25°C	3	month
0°C	12	month

Cured Properties	Nominal Value	Unit
Shore Hardness		
Shore D, 121°C	70	
Shore D, 25°C	80	
Tensile Strength	27.6	MPa

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Recommended distributors for this material

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